| PCN Number: | 20170615005 | 5 | PCN Date: | 06/2 | 20/20: | 17 | |
|---|---------------------------------------|--------------------|---------------------|---------------------|--------------------|----------------------|---------|
| Title: Datasheet | for ADS8588S | | • | | | | |
| ustomer Contact: | PCN Manager | | | De | pt: | Quality Serv | ices |
| hange Type: | | | | | | | |
| Assembly Site | | Design | | | Wafe | er Bump Site | |
| Assembly Process | | Data Sheet | | | | er Bump Materia | al |
| Assembly Materials | | Part number change | | | Wafer Bump Process | | S |
| Mechanical Specification Test Site | | | | Wafer Fab Site | | | |
| Packing/Shipping/Labeling Test Process | | ess | | Wafer Fab Materials | | ; | |
| | | | | | Wafe | er Fab Process | |
| | | lotification | on Details | | | | |
| escription of Cha exas Instruments I | | | | | | | |
| ne following change TEXAS INSTRUMENTS | e history provides | s turther det | ails. | | | | S8588 |
| Changes from Original | (December 2016) to B | Pavision A | | SBAS642 | 2A –DECE | EMBER 2016-REVISED A | PRIL 20 |
| | · · · · · · · · · · · · · · · · · · · | | | | | | |
| | nd ADS8584S from do | | | | | | |
| - | tle | | | | | | |
| • | ntences of <i>Description</i> s | | | | | | |
| | Block Diagram figure: ch | | | | | | |
| Changed Device Fam | nily Comparison Table t | to compare dev | ice family members | 3 | | | 4 |
| Changed AGND to D | GND in <i>DVDD to DGN</i> | D row of Absolເ | ıte Maximum Ratin | gs table | | | |
| Changed minimum sp | pecification from –96 to | –64 in last row | of external referen | ce for E | _G param | neter | |
| Changed x-axis of DO | C Histogram of Codes (| (±10 V), DC His | togram of Codes (± | :5 <i>V)</i> , ar | nd <i>DNL</i> i | for All Codes curves | 18 |
| Changed x-axis of INL vs All Codes (±10 V) and INL vs All Codes (±5 V) curves | | | | | 19 | | |
| Changed second-order to third-order in first paragraph of Overview section | | | | | 2 | | |
| Changed 2nd-order to 3rd-order and RANGE/SDI to RANGE in functional block diagram | | | | | 2 | | |
| - | 3rd-order in Front-End | | | - | | | |
| • | wo in first sentence of | | | • | | • | |
| - · | hird in title and descript | | | | | | |
| • | LPF description in <i>Thin</i> | | | , , | | | |
| Changed second to the | nird in titles of <i>Third-Or</i> | der LPF Magnit | ude Response and | | rder LP | | |
| | | | | | | | |
| ne datasheet numb | er will be changir | | Erom | ı | Chair | go To: | |
| Device Family | | Change | | | Cnan | ge To: | |
| ADS8588S | | SBAS6 | 42 | | | SBAS642A | |
| nese changes may | be reviewed at th | ne datasheet | t links provided | d. | | | |
| ttp://www.ti.com/p | roduct/ADS8588 | <u>S</u> | | | | | |
| eason for Change | e: | | | | | | |
| accurately reflect | device characteri | istics. | | | | | |

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes

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to the actual device.

| Changes to product identification resulting from this PCN: | | | | | | |
|--|--------------|--|--|--|--|--|
| None. | | | | | | |
| Product Affected: | | | | | | |
| ADS8588SIPM | ADS8588SIPMR | | | | | |

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|--------------|--------------------------------|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| Japan | PCNJapanContact@list.ti.com |